# SMD INFRARED LED KEL-1T085C



#### **Features**

Small double-end package

High reliability

Low forward voltage

Good spectral matching to Si photodetector

Pb free

The product itself will remain within RoHS compliant version.

Compliance with EU REACH

### **Application**

PCB mounted infrared sensor

Infrared emitting for miniature light barrier

Floppy disk drive

Optoelectronic switch

Smoke detector

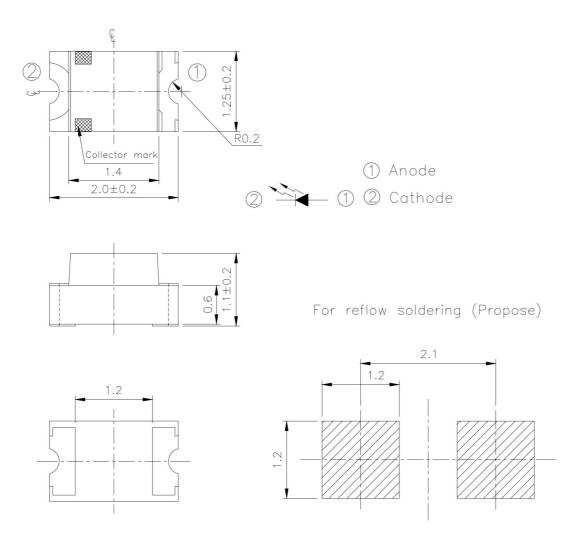
### **Description**

KEL-1T085C is an infrared emitting diode in miniature SMD package which is molded in a water clear plastic With flat top view lens. The device is spectrally matched with silicon photodiode and phototransistor.





#### PACKAGE DIMENSIONS



#### NOTES:

- 1.All dimensions are in millimeters
- 2.Tolerances unless dimensions ±0.1mm
- 3.Suggested pad dimension is just for reference only
  Please modify the pad dimension based on individual need



### ABSOLUTE MAXIMUM RATINGS AT TA =25°C

Parameter	Symbol	Rating	Units
Continuous Forward Current	${ m I_F}$	65	mA
Peak Forward Current *1	$ m I_{FP}$	1.0	A
Reverse Voltage	$V_R$	5	V
Operating Temperature	$T_{opr}$	<b>-25</b> ∼ +85	$^{\circ}\!\mathbb{C}$
Storage Temperature	$T_{stg}$	<b>-</b> 40 ∼ +85	$^{\circ}\!\mathbb{C}$
Soldering Temperature *2	$T_{sol}$	260	$^{\circ}\!\mathbb{C}$
Power Dissipation at(or below)	$P_d$	130	mW
25°C Free Air Temperature			

**Notes:** \*1 Soldering time≦5 seconds.



### **ELECTRICAL OPTICAL CHARACTERISTICS AT TA=25°C**

Parameter	Symbol	Condition	Min.	Typ.	Max.	Units	
Radiant Intensity		I <sub>F</sub> =20mA	0.2	0.8	1		
	Ee	$I_F = 100 mA$ Pulse Width $\leq 100 \mu \text{ s ,Duty} \leq 1\%$	1	4.0	1	mW/sr	
Peak Wavelength	λp	I <sub>F</sub> =20mA	I	940	I	nm	
Spectral Bandwidth	Δλ	I <sub>F</sub> =20mA	I	45	I	nm	
Forward Voltage V <sub>F</sub>		I <sub>F</sub> =20mA	-	1.2	1.5		
	$V_{\mathrm{F}}$	$I_F = 100 mA$ Pulse Width $\leq 100 \mu \text{ s ,Duty} \leq 1\%$	I	1.4	1.8	V	
		$I_F=1A$	I	2.6	4.0		
Reverse Current	$I_R$	$V_R=5V$			10	μΑ	
View Angle	2 \theta 1/2	I <sub>F</sub> =20mA		120	I	deg	



### **Typical Electro-Optical Characteristics Curves**

Fig.1 Forward Current vs.

Ambient Temperature

140 120 100 Forward Current (mA) 80 60 40 20 0 -25 0 20 40 60 80 100 Ambient Temperature (° C)

Fig.3 Peak Emission Wavelength Ambient Temperature

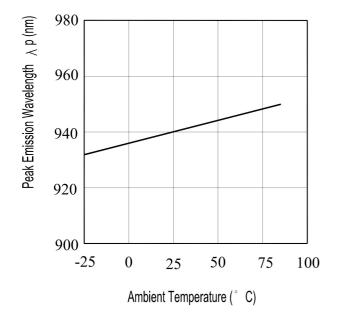


Fig.2 Spectral Distribution

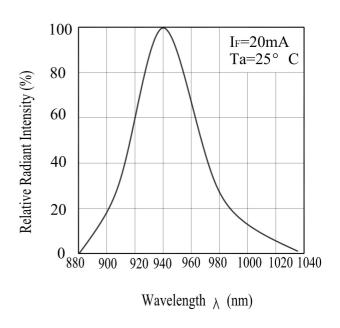
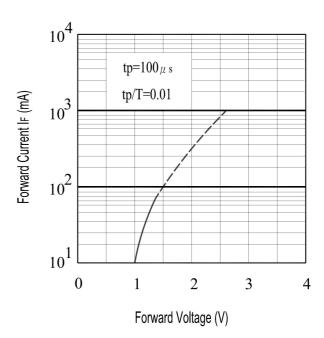


Fig.4 Forward Current vs. Forward Voltage





### **Typical Electro-Optical Characteristics Curves**

Fig.5 Relative Intensity vs.

**Forward Current** 

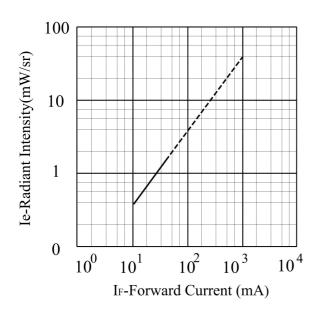


Fig.7 Relative Intensity vs.

Ambient Temperature(°C)

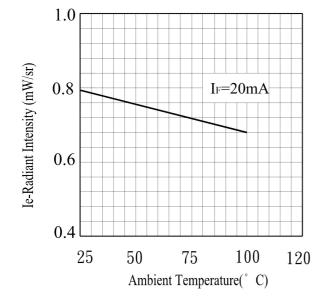


Fig.6 Relative Radiant Intensity vs.

Angular Displacement

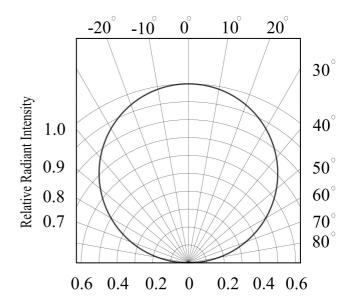
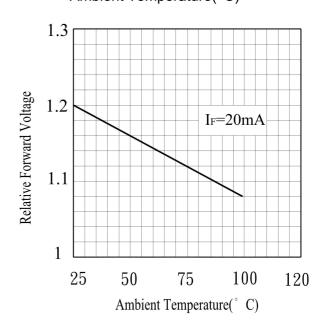


Fig.8 Forward Voltage vs.

Ambient Temperature(°C)





#### **Precautions For Use**

1. Over-current-proof

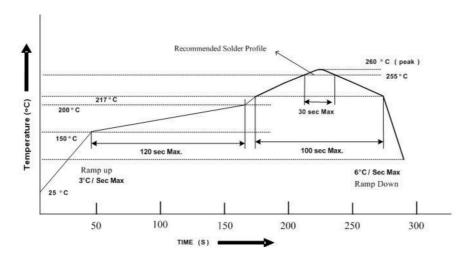
Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

#### 2. Storage

- 2.1 Do not open moisture proof bag before the products are ready to use.
- 2.2 Before opening the package, the LEDs should be kept at 10 ℃~30 ℃ and 90%RH or less.
- 2.3 The LEDs suggested be used within one year.
- 2.4 After opening the package, the devices must be stored at 10°C~30°C and ≤ 60%RH, and used within 168 hours (floor life). If unused LEDs remain, it should be stored in moisture proof packages.
- 2.5 If the moisture absorbent material (desiccant material) has faded or unopened bag has exceeded the shelf life or devices (out of bag) have exceeded the floor life, baking treatment is required.
- 2.6 If baking is required, refer to IPC/JEDEC J-STD-033 for bake procedure or recommend the following conditions:
  - 96 hours at 60°C ± 5°C and < 5 % RH (reeled/tubed/loose units)

#### 3. Soldering Condition

3.1 Pb-free solder temperature profile



- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.

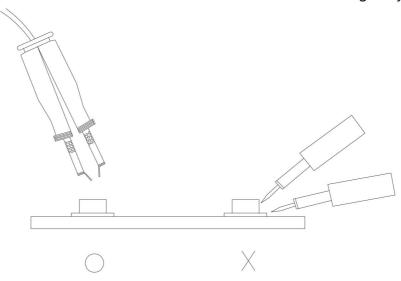


### 4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than  $350^{\circ}$ C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

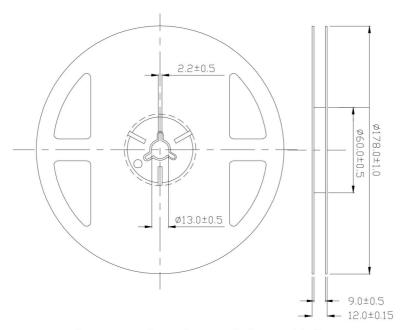
### 5.Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



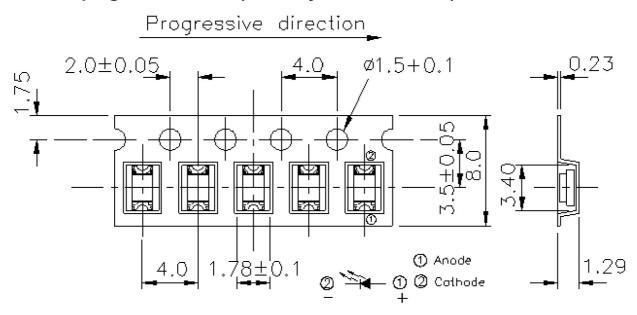


### **Package Dimensions**



Note: The tolerances unless mentioned are ±0.1mm, Unit: mm

### **Carrier Taping Dimensions: (Quantity: 2000PCS/Reel)**



Note: The tolerances unless mentioned are ±0.1mm, Unit: mm



### **Packing Quantity Specification**

- 1. 3000Pcs/1Volume,1Volume/1Bag
- 2. 10Boxes/1Carton

### **Label Form Specification**



· PRODUCT: Part Number

· CODE NO.: Product Serial Number

· QTY: Packing Quantity

· LOT No: Lot Number

· REMARKS:Remarks



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